

Application No.: 10/761,881

LISTING OF CLAIMS

1. (original) An insert ring for a process chamber, comprising:
a ring body defining a central ring opening; and
an annular step provided on said ring body and spaced-apart from said central ring opening.
2. (original) The insert ring of claim 1 wherein said ring body comprises silicon.
3. (original) The insert ring of claim 1 wherein said ring body has a ring body thickness of about 3.5 mm.
4. (original) The insert ring of claim 3 wherein said ring body comprises silicon.
5. (original) The insert ring of claim 1 wherein said step has a step thickness of about 1.5 mm.
6. (original) The insert ring of claim 1 wherein said process chamber comprises etching process chamber.
7. (original) The insert ring of claim 5 wherein said ring body has a ring body thickness of about 3.5 mm.
8. (original) The insert ring of claim 7 wherein said ring body comprises silicon.
9. (original) An insert ring assembly for a process chamber, comprising:
a wafer support for supporting a wafer;
an insert ring encircling said wafer support, said insert ring comprising a ring body defining a central ring opening and an annular step provided on said ring body and spaced-apart from said central ring opening; and a generally perpendicular flow space defined between said insert ring and said wafer support.
10. (original) The insert ring assembly of claim 9 wherein said ring body comprises

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silicon.

11. (original) The insert ring assembly of claim 9 wherein said ring body has a ring body thickness of about 3.5 mm and said step has a step thickness of about 1.5 mm.

12. (original) The insert ring of claim 9 wherein said process chamber comprises etching process chamber.

13. (original) The insert ring assembly of claim 9 further comprising a shadow ring encircling said insert ring.

14. (original) The insert ring assembly of claim 13 wherein said ring body comprises silicon.

15. (original) . The insert ring assembly of claim 13 wherein said ring body has a ring body thickness of about 3.5 mm and said step has a step thickness of about 1.5 mm.

16. (original) The insert ring assembly of claim 15 wherein said ring body comprises silicon.

17. (withdrawn) A method of preventing formation of polymer residues on an inner surface of an insert ring encircling a substrate support during processing of a substrate on the substrate support, comprising the step of:

providing a generally perpendicular flow space between said insert ring and said substrate support by providing a generally step-shaped cross-sectional profile to said insert ring.

18. (withdrawn) The method of claim 17 wherein said insert ring comprises a ring body defining a central ring opening and an annular step provided on said ring body and spaced-apart from said central ring opening.

19. (withdrawn) The method of claim 17 wherein said insert ring comprises quartz.

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20. (withdrawn) The method of claim 19 wherein said insert ring comprises a ring body defining a central ring opening and an annular step provided on said ring body and spaced-apart from said central ring opening.